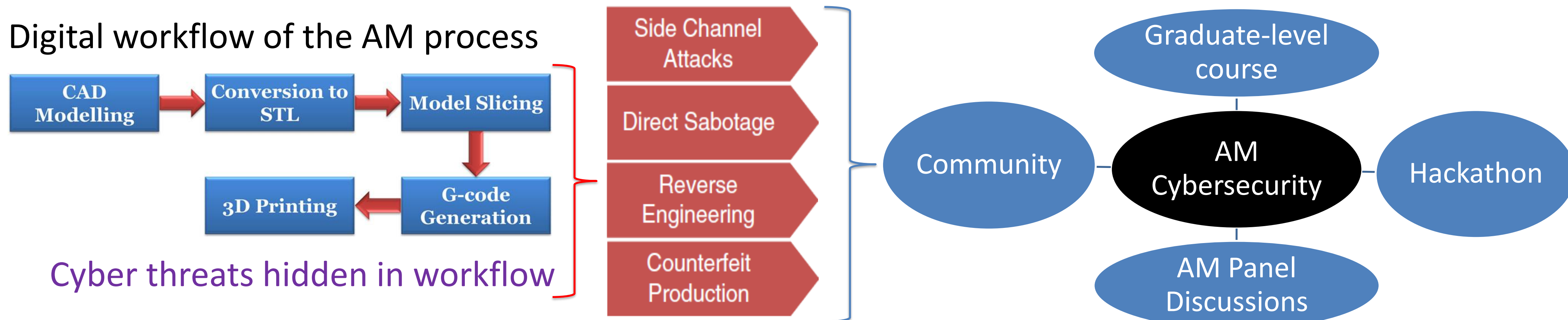


SaTC-Edu: Collaborative: Developing a Comprehensive Education and Training Initiative for Cybersecurity Risks in Additive Manufacturing (AM) Processes

Nikhil Gupta and Ramesh Karri, New York University

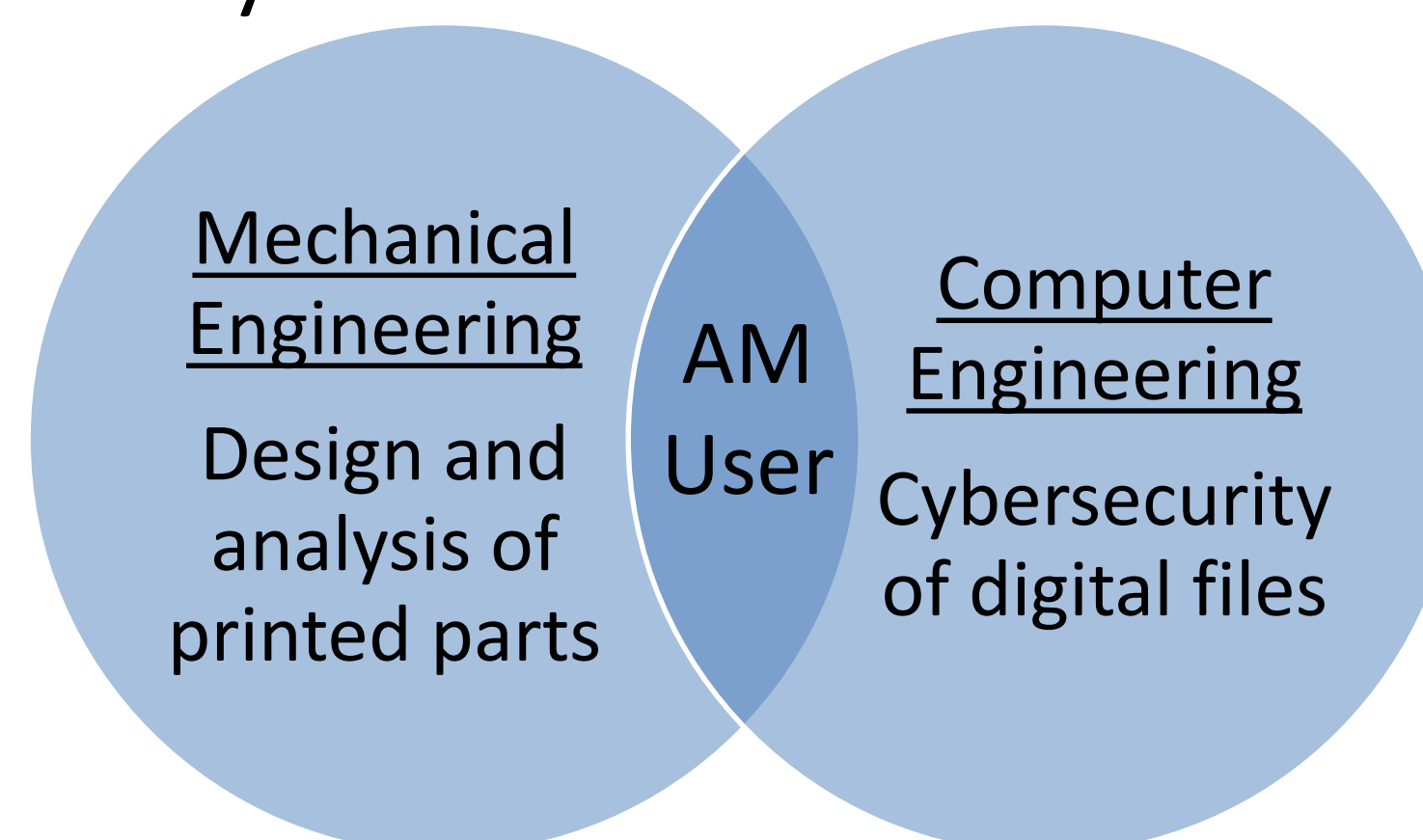
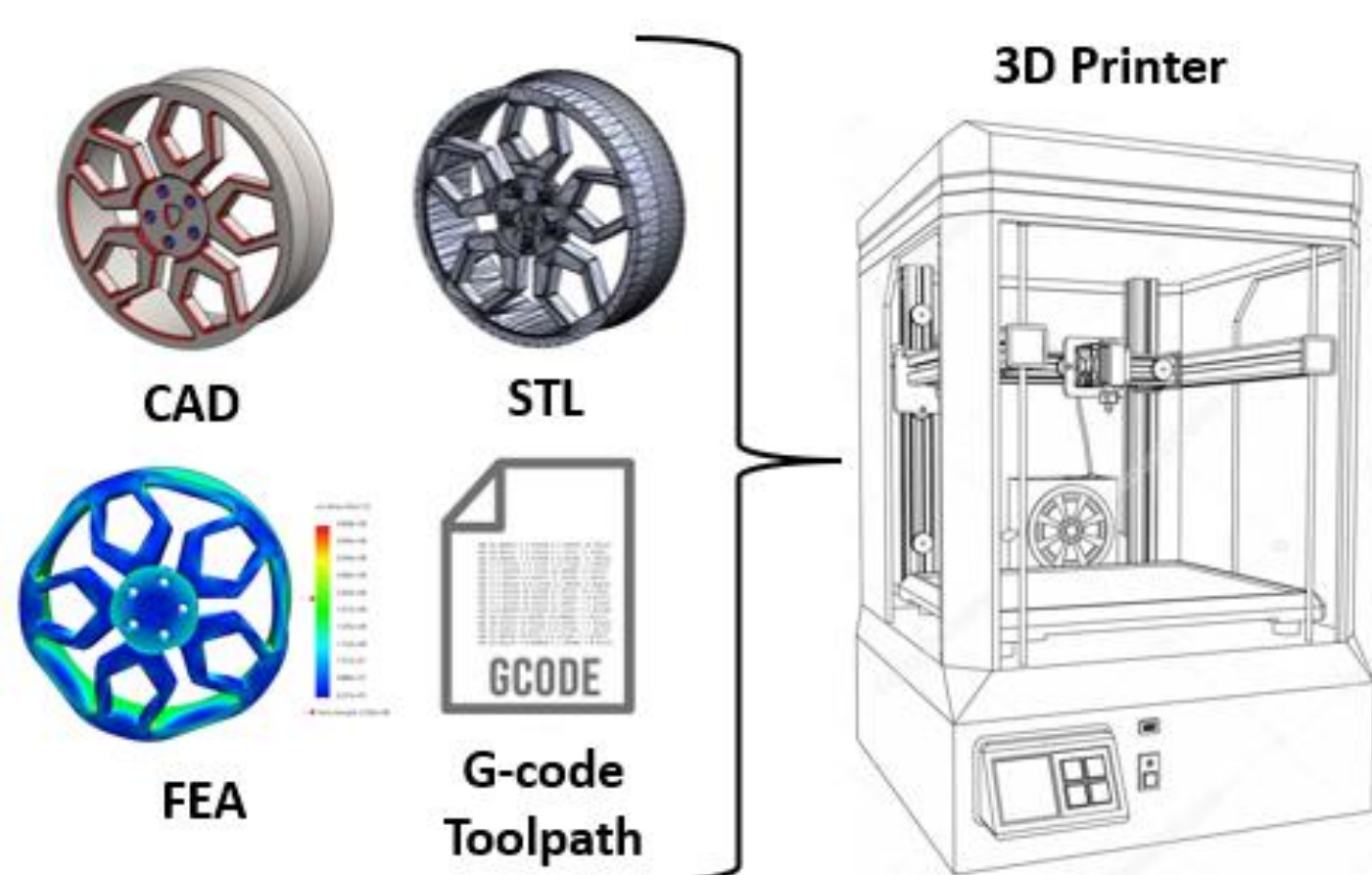
Xiangdong Li and Gaffar Gailani, NY City College of Technology

<https://wp.nyu.edu/cmml/amseceducation/>



Challenge: AM process chain faces a unique set of cyber-physical risks. Project goal is to train a multidisciplinary community of students and professionals in AM cybersecurity.

Scientific Impact: As AM continues to be adopted in various industries, additional training needs to be developed to bridge the gap between mechanical and computer engineers when working in the AM cyber-physical system.



Hack3D (18'-21') – global student cybersecurity competition on additive manufacturing and computer aided design

Virtual Panel Discussion (20'-22') – Networking webinar to gather a manufacturing cybersecurity community from all fields to address the trends and limitation in AM.

CSAW'21 Hack3D

Hack3D Year	2020	2021
# of students	86	1377

AM Panel Discussions

Security Webinars	Panelists	Attendees
8	29	743

Broader Impact: Traditional mechanical engineering curriculum does not cover security risks of cyber-physical systems. This project aims to create educational resources for students and professionals to prepare them for future challenges in cybersecurity for AM.

Education: A graduate level course on AM Security offered in Fall 2020 and 2021. Total enrollment of 22 students with diverse backgrounds. Collaborative effort with NY City Tech in course offerings.

Outreach: Recordings of panel discussion and training programs are available on YouTube for public viewing.

Participation: Obtained a contact list of 2000 people through multiple events on AM cybersecurity.

From 2020 to 2021:

- 7 hackathon competitions
- 8 virtual panel discussions
- 2 semesters of AM Security graduate course offering

